

V1.0.0 GaAs MMIC FET SP4T Absorptive Switch
DC-19GHz

Features

FET SP4T Absorptive design

Frequency: DC-19GHzIsolation: 47dB Typical

Insertion Loss: 1.8dB Typical

Control Voltage: 0/+5V

• Switching Speed: 10ns Typical

• Die Size: 2.05 x 2.0 x 0.1 mm

Typical Applications

- Voltage control
- Fast Switching Speed
- Low Insertion Loss and High Isolation
- Customization available upon request

Electrical Specifications

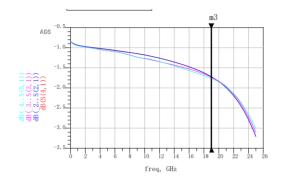
TA = +25°C, VCTL=0/+5V , 1mA ; VEE=-5V , 10mA

| Parameters | Min. | Тур. | Max. | Units |
|----------------------------------|------|------|------|-------|
| Frequency | DC | | 19 | GHz |
| Insertion Loss | | 1.8 | | dB |
| Isolation | | 47 | | dB |
| Input Return Loss | | -19 | | dB |
| Output Return Loss | | -19 | | dB |
| P1dB - Output 1dB Compression | | 21 | | dBm |
| IIP3-Input Third Order Intercept | | 37 | | dBm |
| Switching Speed | | 10 | | ns |

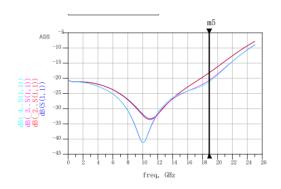


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Insertion Loss vs. Frequency

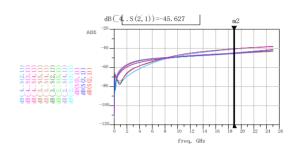


Input Return Loss vs. Frequency

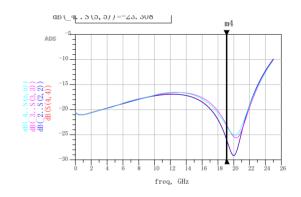




Isolation vs. Frequency



Output Return Loss vs. Frequency

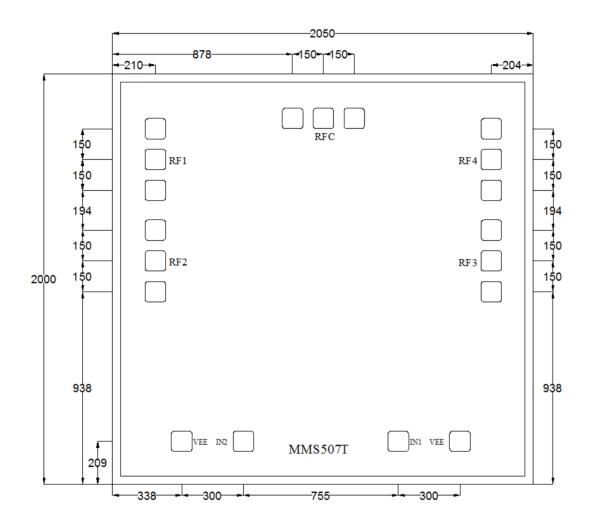




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Outline Drawing:

All Dimensions in µm



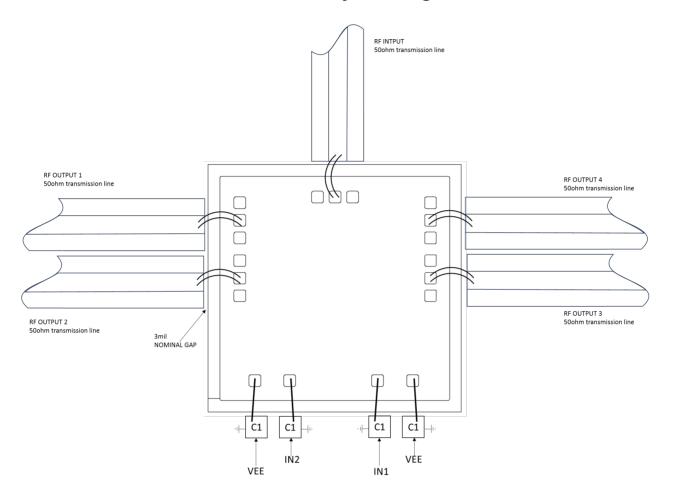
Truth Table

| Voltage | | | State | | | |
|---------|-----|-----|-------|-----|-----|-----|
| VEE | IN1 | IN2 | RF1 | RF2 | RF3 | RF4 |
| -5V | 0V | 0V | ON | OFF | OFF | OFF |
| -5V | 0V | 5V | OFF | ON | OFF | OFF |
| -5V | 5V | 0V | OFF | OFF | ON | OFF |
| -5V | 5V | 5V | OFF | OFF | OFF | ON |



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Assembly Drawing



Notes:

1. Die thickness:100µm

2. Typical bond pad is 100*100µm²

3. Bond pad mentalization: Gold

4. Backside metallization: Gold

5. Backside of the die (GND)

6. No connection required for unlabeled bond pads

| Item | Description |
|------|---|
| C1 | 39pF Capacitor Example: Skyworks Part: SC10002430 |

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